

1 ABSTRACT OF THE DISCLOSURE

2 Conductive lines, such as co-axial lines, integrated circuitry
3 incorporating such conductive lines, and methods of forming the same
4 are described. In one aspect, a substrate having an outer surface is
5 provided. A masking material is formed over the outer surface and
6 subsequently patterned to form a conductive line pattern. An inner
7 conductive layer is formed within the conductive line pattern, followed
8 by formation of a dielectric layer thereover and an outer conductive
9 layer over the dielectric layer. Preferred implementations include
10 forming the inner conductive layer through electroplating, or alternatively,
11 electroless plating techniques. Other preferred implementations include
12 forming the dielectric layer from suitable polymer materials having
13 desired dielectric properties. A vapor-deposited dielectric layer of
14 Parylene is one such preferred dielectric material.

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